

Special Issue

Advances in Polyimide Films: Preparation, Properties and Applications

Message from the Guest Editor

Polyimide films have experienced rapid development in recent years, the major emphasis being on engineering applications. The ability of polyimide films to maintain their excellent electrical, thermal, physical and chemical properties over a wide temperature range has opened new design and application areas to plastic films. The polyimide films have been used in a variety of electrical and electronic insulation applications in various industries such as aerospace, energy, automotive and electronics. There has recently been an intense effort to develop flexible and transparent plastic substrates suitable for applications in conformable and roll-up displays. Polyimide films have been regarded as a potential candidate for the substrate owing their excellent mechanical, thermal, chemical and electrical properties. This Special Issue is dedicated to recent advances in research and development of polyimide films. Research articles on the latest research work in this area, with emphasis on preparation, properties or applications are invited.

- Synthesis method
- Polyimide films
- Composite films
- Preparation
- Properties
- Applications

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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